



PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN Number: **11-19**

Date Issued: **September 26, 2011**

Product(s) Affected: **See below**

Date Effective: **Nov 1, 2011**

Means of Distinguishing Changed Devices:

- Product Mark
 Back Mark
 Date Code: **See note below**
 Other

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Attachment: Yes; No

1. **List of affected products in Excel**
2. **Copper Bond Wire Qual Reports**

Description and Purpose of Change:

Adding packages and part numbers to the list of already qualified copper bond wire process covered by PCN # 10-04, 11-13 and 11-18. For reference, these PCN's can be found at <http://www.pericom.com/quality/pcn.php>

Additional Qualified Packages covered by this PCN are:

- ZD24, ZH20, FC64, FB48 and FD100 at Greatek
- NJ100 at ASEM

For reference on the description of these packages, pls refer to <http://www.pericom.com/products/packaging/mechanicals.php>

Qualifications of other assembly sites doing the same packages are in-progress. No further PCN will be issued when they complete and pass the Qual but Pericom will only ship copper wire assembled products from qualified assembly sites.

Product electrical characterization on representative device showed that performance of the product meets the existing datasheet specification and was comparable to gold wire performance. There is no change in moisture sensitivity level and is still RoHS 6 compliant. We do not anticipate any application issue with the material change.

If customers require samples for evaluation, pls. request ASAP from your Pericom Sales contact as some of the affected devices were not built ahead of this PCN. If additional time to build and to perform sample testing is needed, an extension can be requested.

On effective date, product assembled with Gold and Copper wire can be shipped during the transition period until Gold inventory is depleted. However, Pericom will not mix Gold and Copper in one packaging (i.e. tray or tape and reel.)

- Die Technology
 Wafer Fabrication
 Assembly Process: Copper Wire Process
 Equipment
 Material: Copper Wire
 Testing
 Manufacturing Site
 Data Sheet

PCN # 11-19 Affected P/N		
Pericom Part Number	Package Type	Package Code
PI5USB2058ZHEX	TQFN	ZH20
PI5USB2058ZHE	TQFN	ZH20
PI3USB14-AZHEX	TQFN	ZH20
PI3USB14-AZHE	TQFN	ZH20
PI3CH401ZHEX	TQFN	ZH20
PI3CH401ZHE	TQFN	ZH20
PI2EQX3431ZHEX	TQFN	ZH20
PI2EQX3431ZHE	TQFN	ZH20
PI7C9X20508GPBNDE	BGA	ND256
PI7C9X20505GPBNDE	BGA	ND256
PI7C9X130DNDE	BGA	ND256
PI2EQX5804DNJEX	BGA	NJ100
PI2EQX5804DNJE	BGA	NJ100
PI90SD1636DFCEX	QFP	FC64
PI90SD1636DFCE	QFP	FC64
PI90SD1636CFCEX	QFP	FC64
PI90SD1636CFCE	QFP	FC64
PI6C487016FBEX	QFP	FB48
PI6C487016FBE	QFP	FB48

- Note:**
- The distinguishing means for products assembled using copper wire will be the addition of bar on top of the last character of the datecode marking.

Examples:

Gold Wire

Copper Wire



Customer Acknowledgement of Receipt:

Customer: _____

Name: _____

Title: _____

Date: _____

eMail: _____

Phone: _____

Fax: _____

Approval for shipments prior to effective date

Customer Comments (Optional): _____